

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	107	(clean\$3 or treat\$3 or wash\$3) same (drop \$4 with (hit\$3 or imping\$3 or bombard\$3) with (size or diameter or radius or dimension))	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/14 10:49
S2	117	(clean\$3 or treat\$3 or wash\$3) same (drop \$4 with (hit\$3 or imping\$3 or bombard\$3) with (size or diameter or radius or dimension))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 10:49
S3	28	S2 and (substrate or semiconductor or wafer or article or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 10:50
S4	117	(clean\$3 or treat\$3 or wash\$3) same (drop \$4 with (hit\$3 or imping\$3 or bombard\$3) with (size or diameter or radius or dimension))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 10:50
S5	28	S4 and (substrate or semiconductor or wafer or article or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 10:51
S6	1388	((volume adj median adj diameter) or VMD)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 10:51
S7	545	S6 and (substrate or semiconductor or wafer or article or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 10:53
S9	1	("20070169793").PNL	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/14 10:56
S10	7	S7 and ((bi\$1fluid or (two adj fluid)) adj nozzle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 11:04
S11	294	S7 and (nozzle or spray\$3 or mist\$3 or atomiz\$3 or atomiz\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 11:06
S13	1	("5484471").PNL	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/14 11:11
S14	24	S6 and ((bi\$1fluid or (two adj fluid)) adj nozzle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 11:11

S16	10373	134/2,25.4,26,31,34,37,42,902.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/14 13:14
S17	5	S6 and S16	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/14 13:14
S18	5227	S16 and (nozzle or spray\$3 or mist\$3 or atomiz\$3 or atomis\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 13:14
S19	3396	S18 and (size or diameter or radius or dimension)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 13:14
S20	2339	S19 and (substrate or semiconductor or wafer or article or workpiece)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 13:15
S21	0	438/906.ccls. and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 13:16
S22	6	*438"/\$.ccls. and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 13:17
S23	7	*156"/\$.ccls. and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 13:18
S24	7	*134"/\$.ccls. and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2008/03/14 13:18

3/14/2008 3:15:50 PM

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